

# DATA SHEET

## **BYC8B-600**

Rectifier diode

ultrafast, low switching loss

Product specification

December 2024



**WeEn**

WeEn Semiconductors

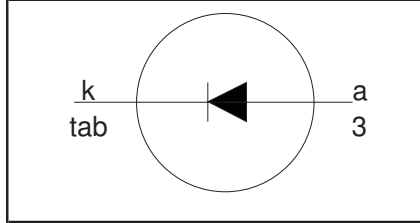
# Rectifier diode ultrafast, low switching loss

**BYC8B-600**

## FEATURES

- Extremely fast switching
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses in associated MOSFET

## SYMBOL



## QUICK REFERENCE DATA

$V_R = 600\text{ V}$
$V_F \leq 1.85\text{ V}$
$I_{F(AV)} = 8\text{ A}$
$t_{rr} = 19\text{ ns (typ)}$

## APPLICATIONS

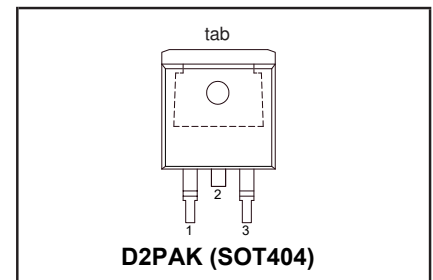
- Active power factor correction
- Half-bridge lighting ballasts
- Half-bridge/ full-bridge switched mode power supplies.

The BYC8B-600 is supplied in the SOT404 surface mounting package.

## PINNING

PIN	DESCRIPTION
1	no connection
2	cathode <sup>1</sup>
3	anode
tab	cathode

## SOT404



## LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{RRM}$	Peak repetitive reverse voltage		-	600	V
$V_{RWM}$	Crest working reverse voltage		-	600	V
$V_R$	Continuous reverse voltage	$T_{mb} \leq 110\text{ °C}$	-	500	V
$I_{F(AV)}$	Average forward current	$\delta = 0.5$ ; with reappplied $V_{RRM(max)}$ ; $T_{mb} \leq 82\text{ °C}$	-	8	A
$I_{FRM}$	Repetitive peak forward current	$\delta = 0.5$ ; with reappplied $V_{RRM(max)}$ ; $T_{mb} \leq 82\text{ °C}$	-	16	A
$I_{FSM}$	Non-repetitive peak forward current.	$t = 10\text{ ms}$ $t = 8.3\text{ ms}$ sinusoidal; $T_j = 150\text{ °C}$ prior to surge with reappplied $V_{RWM(max)}$	-	55	A
$T_{stg}$	Storage temperature		-40	150	°C
$T_j$	Operating junction temperature		-	150	°C

## THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base		-	-	2.2	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	minimum footprint, FR4 board	-	50	-	K/W

<sup>1</sup> it is not possible to make connection to pin 2 of the SOT404 package

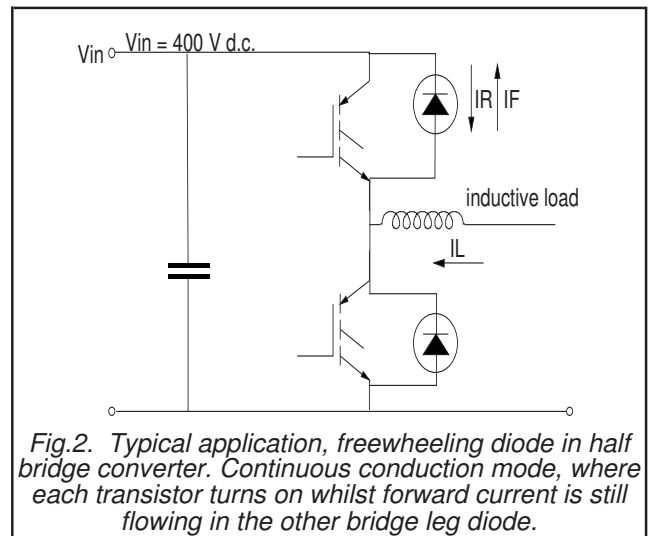
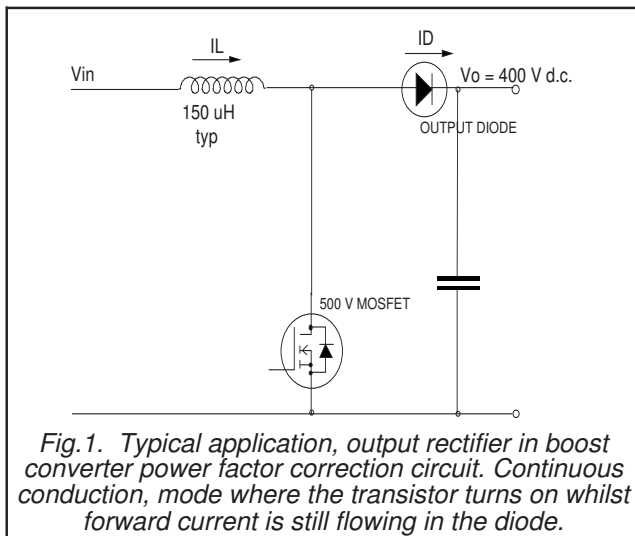
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**ELECTRICAL CHARACTERISTICS**

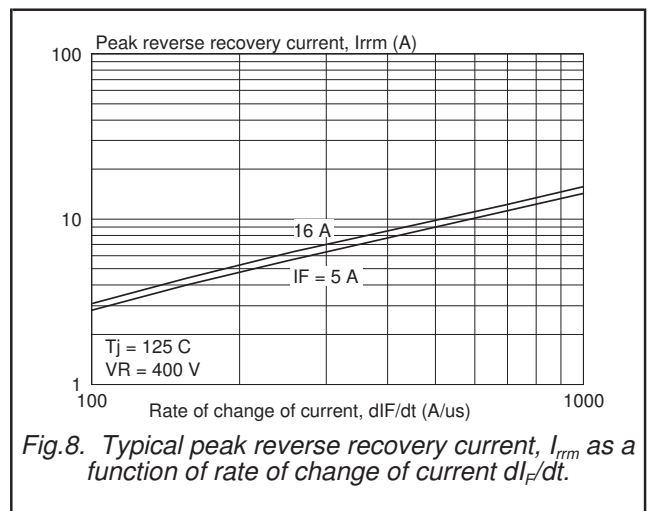
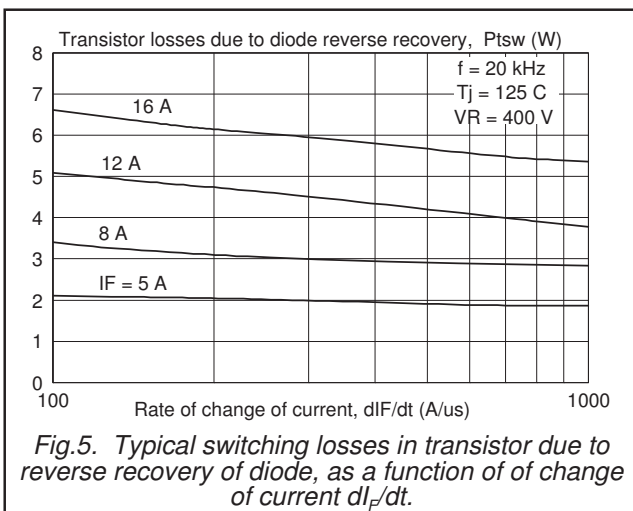
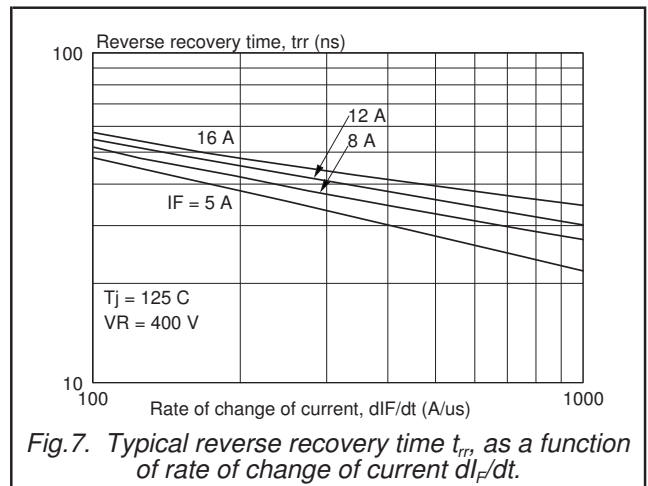
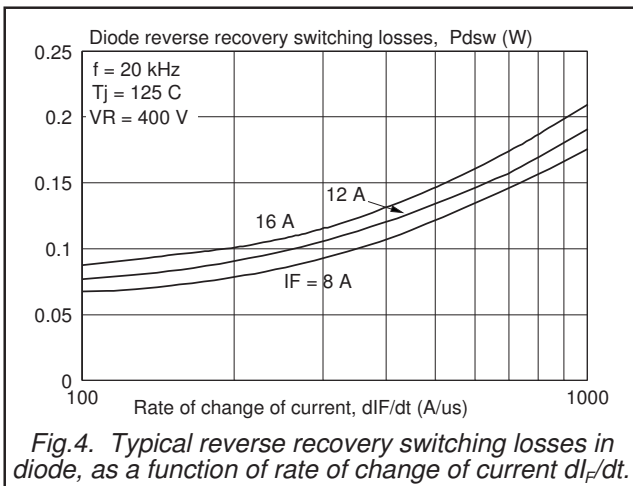
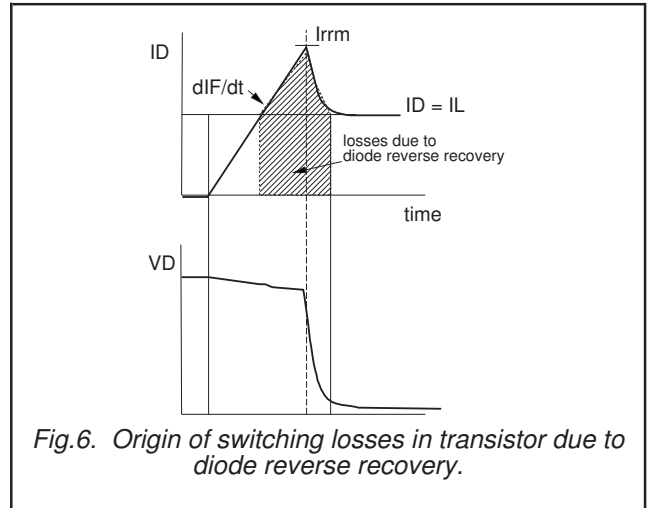
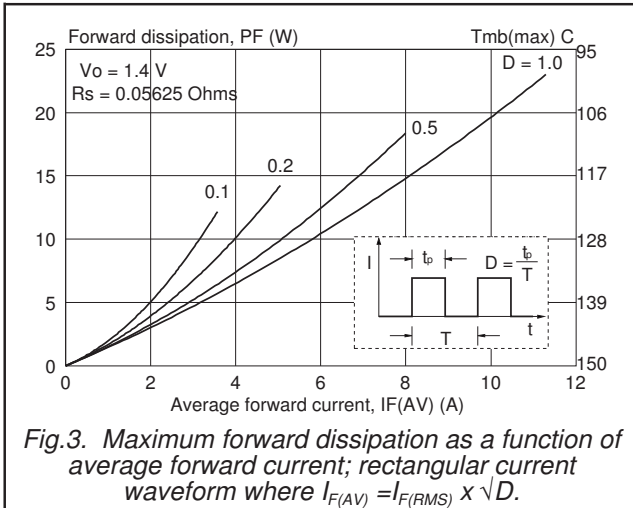
$T_j = 25\text{ }^\circ\text{C}$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_F$	Forward voltage	$I_F = 8\text{ A}; T_j = 150\text{ }^\circ\text{C}$	-	1.4	1.85	V
		$I_F = 16\text{ A}; T_j = 150\text{ }^\circ\text{C}$	-	1.7	2.3	V
		$I_F = 8\text{ A}; V_R = 600\text{ V}$	-	2.0	2.9	V
$I_R$	Reverse current	$V_R = 600\text{ V}$	-	9	150	$\mu\text{A}$
		$V_R = 500\text{ V}; T_j = 100\text{ }^\circ\text{C}$	-	1.1	3.0	mA
$t_{rr}$	Reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 50\text{ A}/\mu\text{s}$	-	30	52	ns
$t_{rr}$	Reverse recovery time	$I_F = 8\text{ A}; V_R = 400\text{ V}; dI_F/dt = 500\text{ A}/\mu\text{s}$	-	19	-	ns
$t_{rr}$	Reverse recovery time	$I_F = 8\text{ A}; V_R = 400\text{ V}; dI_F/dt = 500\text{ A}/\mu\text{s}; T_j = 100\text{ }^\circ\text{C}$	-	32	40	ns
$I_{rrm}$	Peak reverse recovery current	$I_F = 8\text{ A}; V_R = 400\text{ V}; dI_F/dt = 50\text{ A}/\mu\text{s}; T_j = 125\text{ }^\circ\text{C}$	-	1.5	5.5	A
$I_{rrm}$	Peak reverse recovery current	$I_F = 8\text{ A}; V_R = 400\text{ V}; dI_F/dt = 500\text{ A}/\mu\text{s}; T_j = 125\text{ }^\circ\text{C}$	-	9.5	12	A
$V_{fr}$	Forward recovery voltage	$I_F = 10\text{ A}; dI_F/dt = 100\text{ A}/\mu\text{s}$	-	8	10	V



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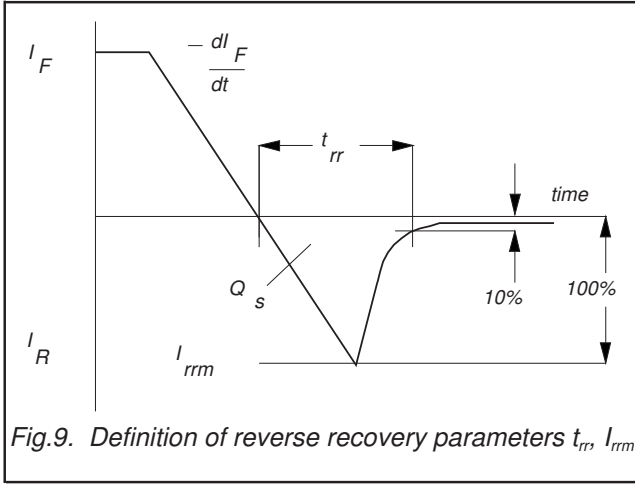


Fig.9. Definition of reverse recovery parameters  $t_{rr}$ ,  $I_{rrm}$

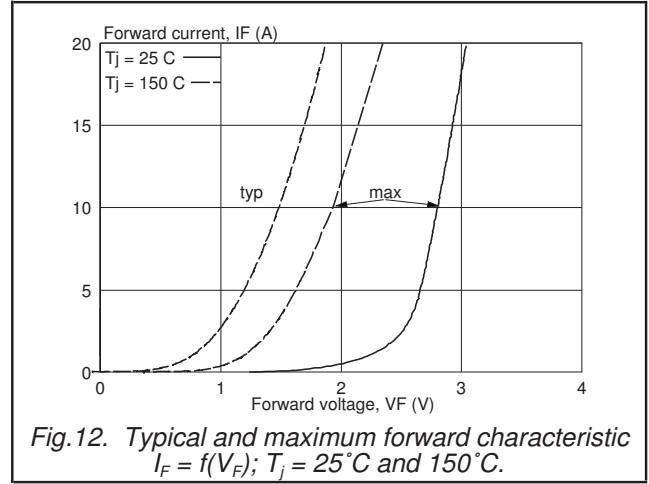


Fig.12. Typical and maximum forward characteristic  $I_F = f(V_F)$ ;  $T_J = 25\text{ C}$  and  $150\text{ C}$ .

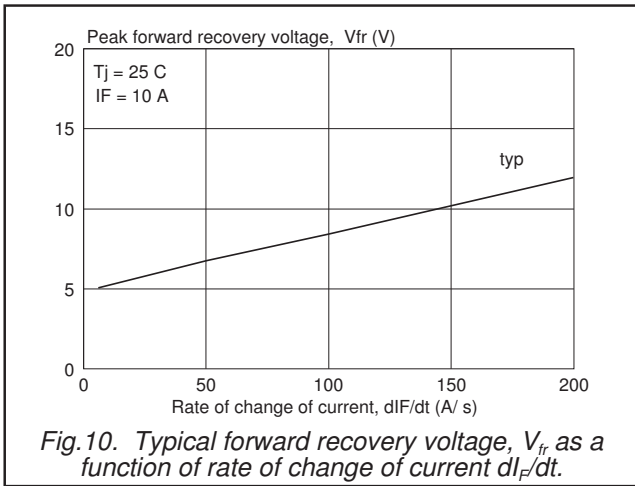


Fig.10. Typical forward recovery voltage,  $V_{fr}$  as a function of rate of change of current  $dI_F/dt$ .

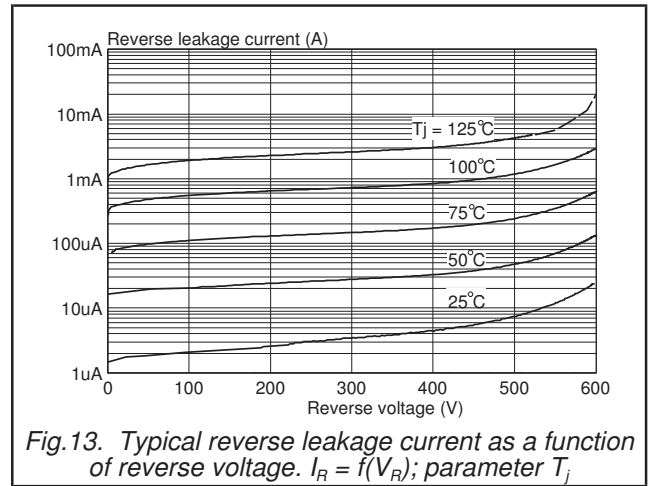


Fig.13. Typical reverse leakage current as a function of reverse voltage.  $I_R = f(V_R)$ ; parameter  $T_J$

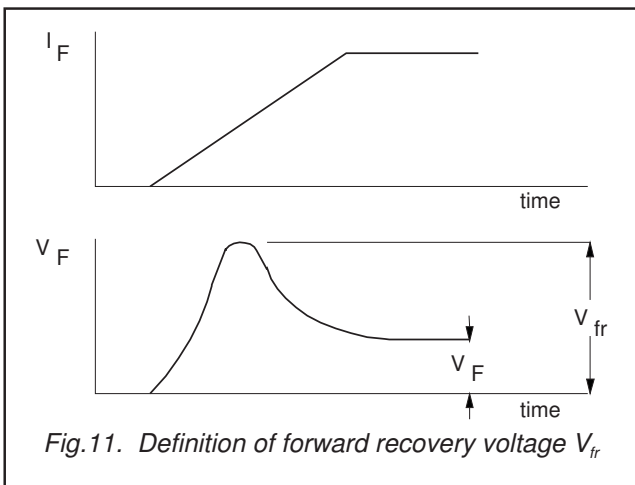


Fig.11. Definition of forward recovery voltage  $V_{fr}$

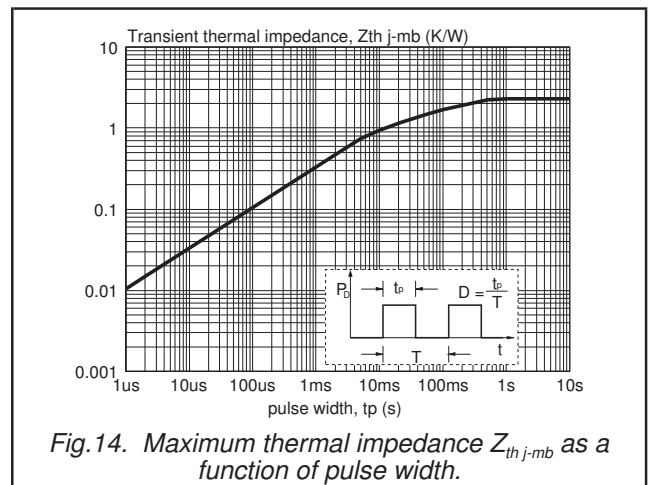


Fig.14. Maximum thermal impedance  $Z_{th\ j-mb}$  as a function of pulse width.

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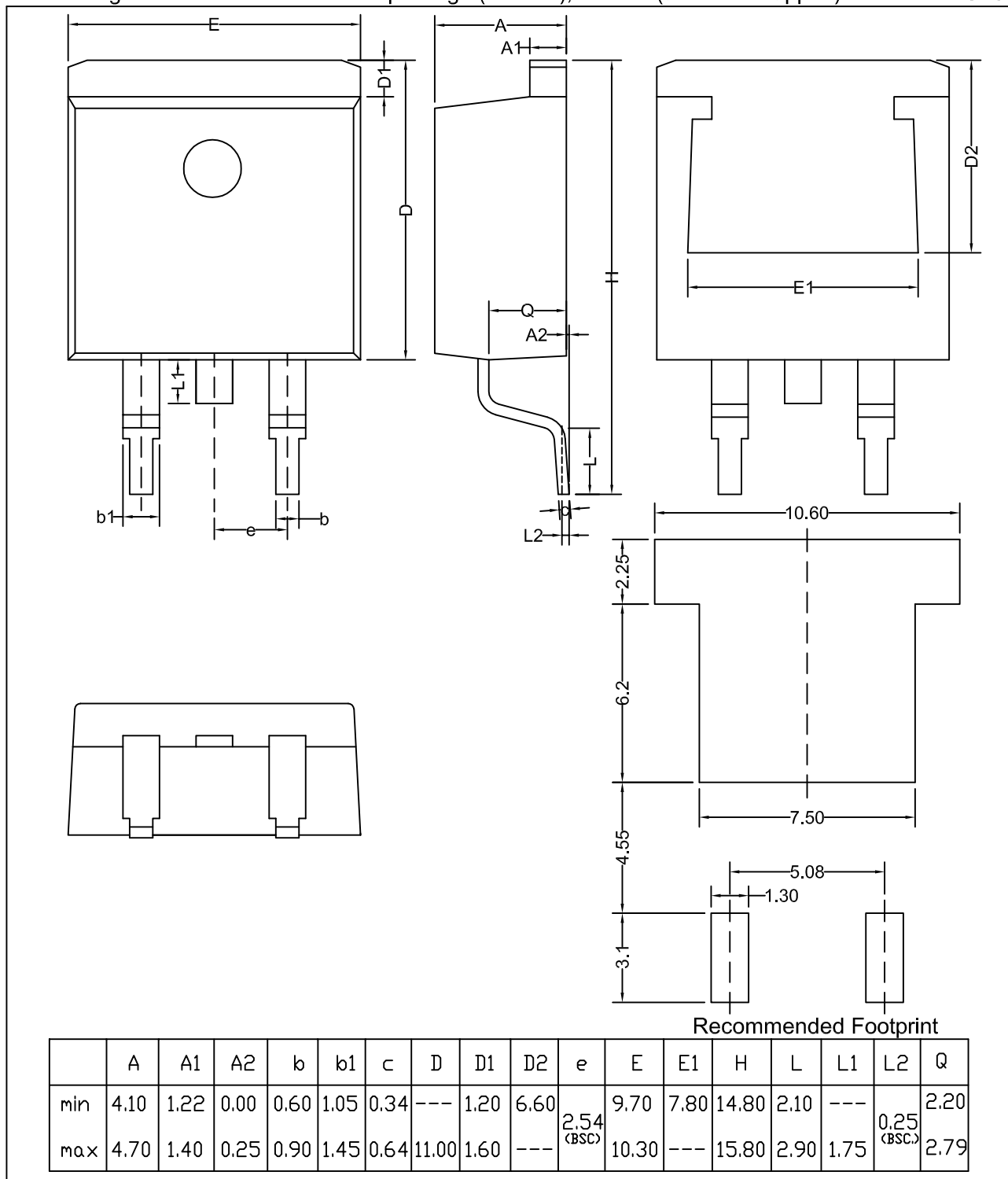
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**MECHANICAL DATA**

Assembly factory: N

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

TO263



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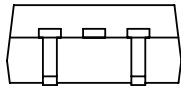
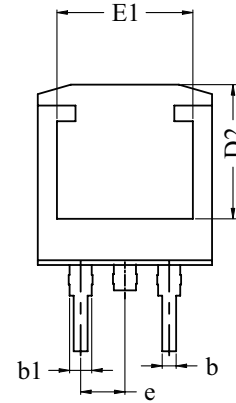
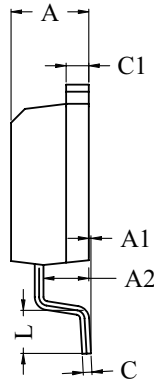
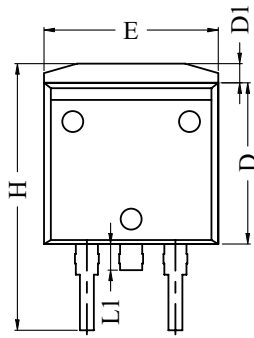
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**MECHANICAL DATA**

Assembly factory: P

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

TO263



Dim	All Dimensions in Millimeters		
	Min	Typ	Max
A	4.30	4.46	4.60
A1	0	0.13	0.25
A2	2.50	2.60	2.70
b	0.70	0.80	0.90
b1	1.10	1.27	1.45
C	0.40	0.52	0.60
C1	1.17	1.30	1.40
D	9.10	9.25	9.40
D1	1.00	1.10	1.30
D2	7.40	7.70	8.00
E	9.80	10.00	10.20
E1	7.60	7.80	8.00
e	2.54 BSC		
H	14.80	15.30	15.80
L	2.10	2.47	2.80
L1	1.30	1.50	1.70

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Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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